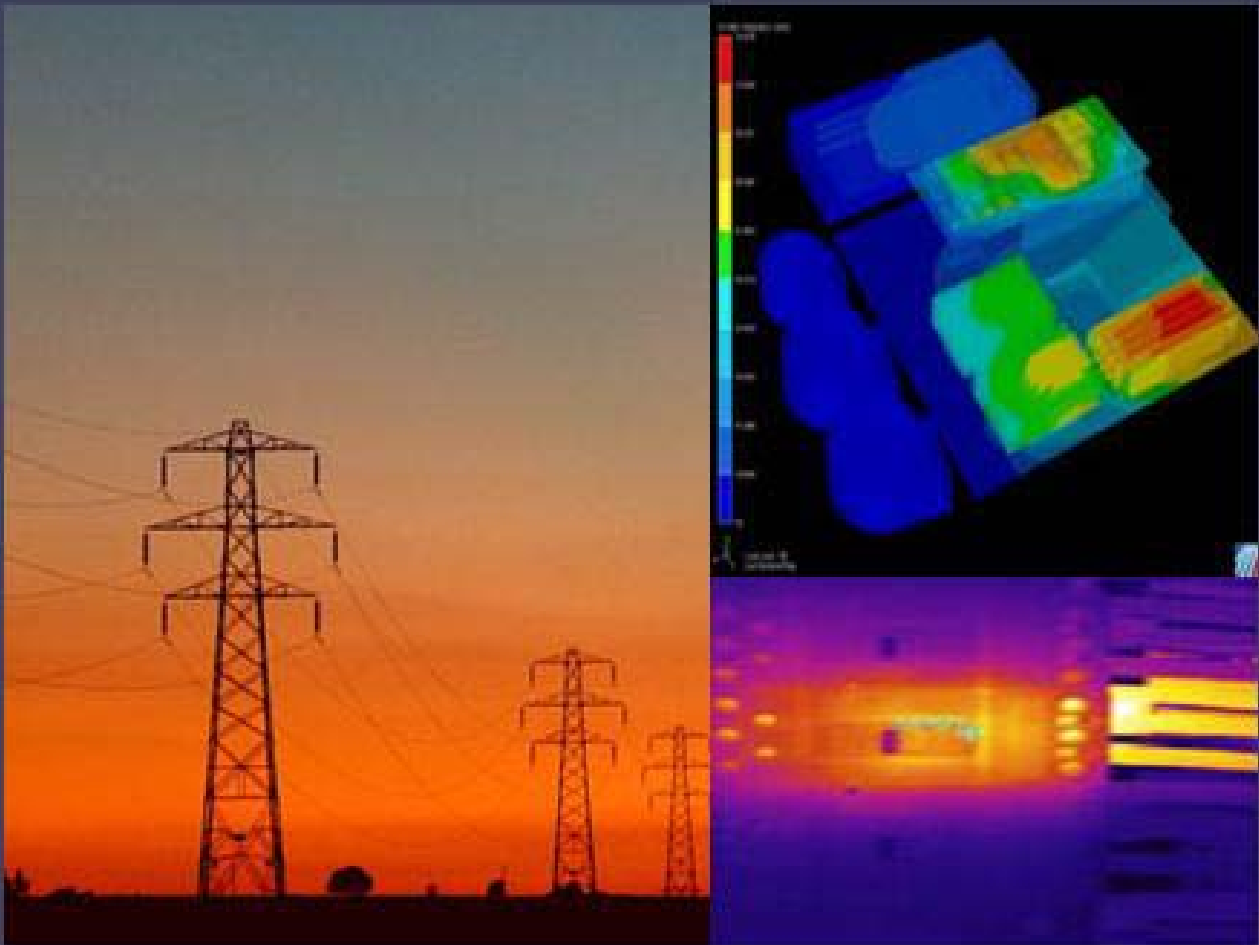


An Industry Report  
NGDC Report Series 2008



# Next Gen Datacenters: **Power & Cooling**

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## Next-Generation Data Centers – Power & Cooling

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